APPLICATION DATA SHEET

Electronic Version v14 Stylesheet Version v14.0

> Title of Invention

STRIP-FABRICATED FLIP CHIP IN PACKAGE AND FLIP CHIP IN SYSTEM HEAT SPREADER ASSEMBLIES AND FABRICATION METHODS THEREFOR

Application Type:

regular, utility

Attorney Docket Number: 27-013

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22898

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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

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Page 4 of 4

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